

**N - CHANNEL ENHANCEMENT MODE
POWER MOS TRANSISTOR**

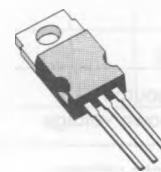
TYPE	V _{DSS}	R _{DS(on)}	I _D
SGSP301	100 V	1.4 Ω	2.0 A

- HIGH SPEED SWITCHING APPLICATIONS
- GENERAL PURPOSE APPLICATIONS
- ULTRA FAST SWITCHING
- EASY DRIVE FOR REDUCED COST AND SIZE

INDUSTRIAL APPLICATIONS:

- GENERAL PURPOSE SWITCHING

N - channel enhancement mode POWER MOS field effect transistor. Easy drive and very fast switching times make this POWER MOS transistor ideal for high speed switching applications. Typical applications include general purpose low voltage switching, solenoid driving, motor and lamp control, switching power supplies, and driving, bipolar power switching transistors.


TO-220
**INTERNAL SCHEMATIC
DIAGRAM**

ABSOLUTE MAXIMUM RATINGS

V _{DS}	Drain-source voltage (V _{GS} = 0)	100	V
V _{DGR}	Drain-gate voltage (R _{GS} = 20 kΩ)	100	V
V _{GS}	Gate-source voltage	±20	V
I _D	Drain current (cont.) at T _c = 25°C	2.0	A
I _D	Drain current (cont.) at T _c = 100°C	1.2	A
I _{DM} (*)	Drain current (pulsed)	6	A
I _{DLM} (*)	Drain inductive current, clamped	6	A
P _{tot}	Total dissipation at T _c < 25°C	18	W
	Derating factor	0.144	W/°C
T _{stg}	Storage temperature	- 65 to 150	°C
T _j	Max. operating junction temperature	150	°C

(*) Pulse width limited by safe operating area

THERMAL DATA

$R_{thj \cdot case}$	Thermal resistance junction-case	max	6.95	°C/W
T_L	Maximum lead temperature for soldering purpose		275	°C

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^\circ C$ unless otherwise specified)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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OFF

$V_{(BR) DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu A$	$V_{GS} = 0$	100			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$			250		μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{DS} = \text{Max Rating} \times 0.8$	$T_c = 125^\circ C$	1000			μA
					± 100	nA	

ON (*)

$V_{GS \text{ (th)}}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu A$	2		4	V
$R_{DS \text{ (on)}}$	Static drain-source on resistance	$V_{GS} = 10 V$	$I_D = 1.2 A$			1.4	Ω
		$V_{GS} = 10 V$	$I_D = 1.2 A$	$T_c = 100^\circ C$		2.8	Ω

DYNAMIC

g_s	Forward transconductance	$V_{DS} = 25 V$	$I_D = 1.2 A$	0.5			mho
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 V$ $V_{GS} = 0$	$f = 1 MHz$	90	125 45 30	pF pF pF	

SWITCHING

$t_d \text{ (on)}$	Turn-on time	$V_{DD} = 50 V$	$I_D = 1.2 A$	10	15	ns
t_r	Rise time	$V_i = 10 V$	$R_i = 4.7 \Omega$	20	30	ns
$t_d \text{ (off)}$	Turn-off delay time	(see test circuit)		15	20	ns
t_f	Fall time			15	20	ns

ELECTRICAL CHARACTERISTICS (Continued)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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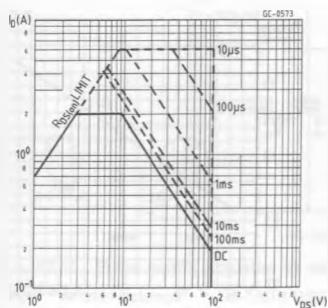
SOURCE DRAIN DIODE

I_{SD}	Source-drain current			2.0	A
$I_{SDM} (\textcircled{a})$	Source-drain current (pulsed)			6	A
V_{SD}	Forward on voltage	$I_{SD} = 2.5 \text{ A}$	$V_{GS} = 0$		V
t_{rr}	Reverse recovery time	$I_{SD} = 2.5 \text{ A}$	$V_{GS} = 0$	90	ns

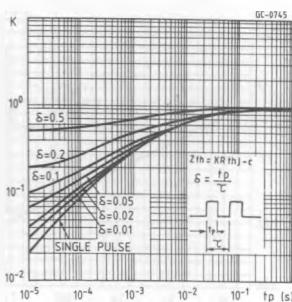
(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

(*) Pulse width limited by safe operating area

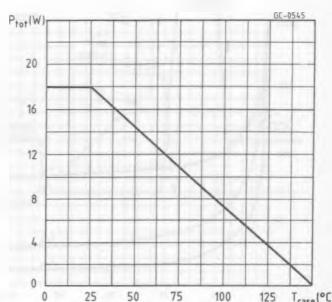
Safe operating areas



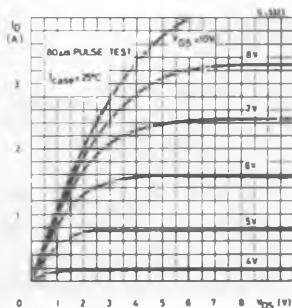
Thermal impedance



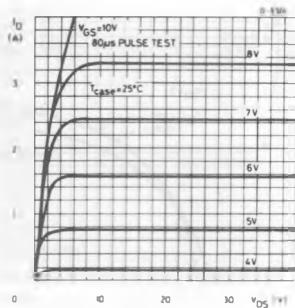
Derating curve



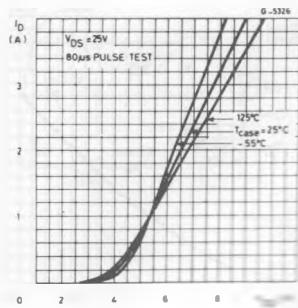
Output characteristics



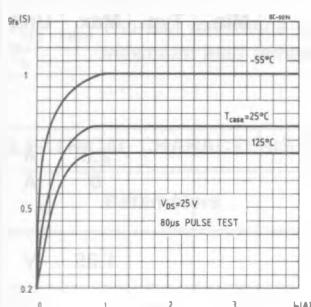
Output characteristics



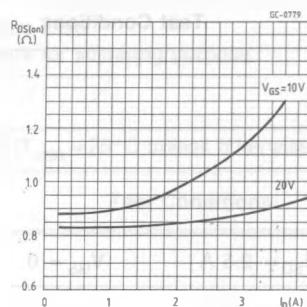
Transfer characteristics



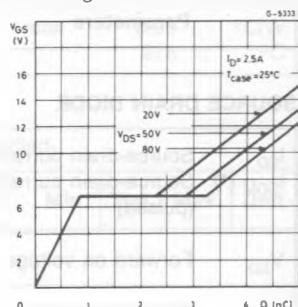
Transconductance



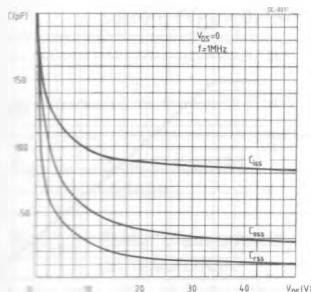
Static drain-source on resistance



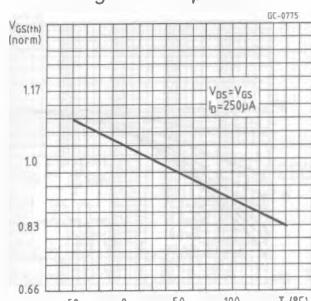
Gate charge vs gate-source voltage



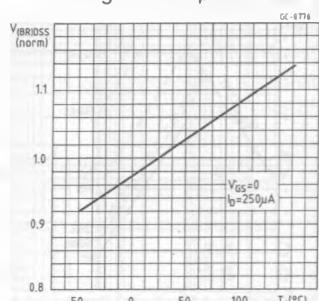
Capacitance variation



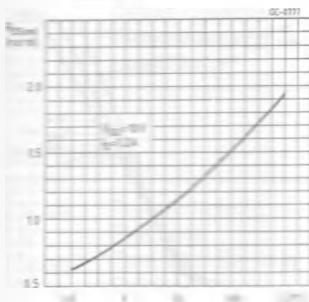
Normalized gate threshold voltage vs temperature



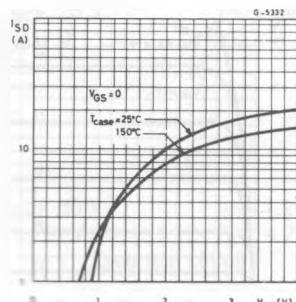
Normalized breakdown voltage vs temperature



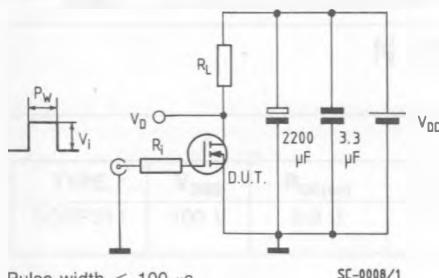
Normalized on resistance vs temperature



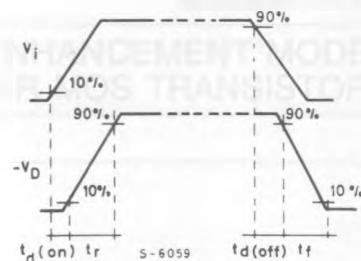
Source-drain diode forward characteristics



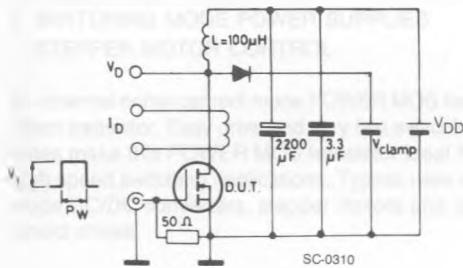
Switching times test circuit for resistive load



Switching time waveforms for resistive load

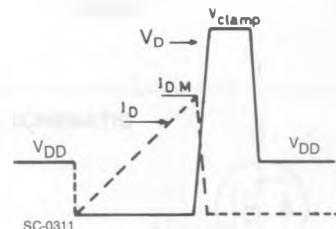


Clamped inductive load test circuit

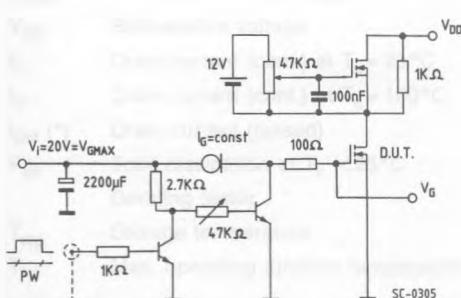


$V_i = 12 \text{ V}$ - Pulse width: adjusted to obtain specified I_{DM} . $V_{clamp} = 0.75 V_{(BR) DSS}$.

Clamped inductive waveforms



Gate charge test circuit



PW adjusted to obtain required V_G

Body-drain diode t_{rr} measurement
Jedec test circuit